

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	ADG/23/14027
1.3 Title of PCN	SPC58xN8xC3x (FG84): BGA 17x17 Activation of ASE as Additional Assembly Plant
1.4 Product Category	see list
1.5 Issue date	2023-05-09

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Luca RODESCHINI
2.2.2 Marketing Manager	Matteo MOIOLI
2.2.3 Quality Manager	Alberto MERVIC

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Subcon ASE - Taiwan receiving Plant

4. Description of change

	Old	New
4.1 Description	ST Kirkop - Malta Assy Plant	ST Kirkop - Malta and ASE - Taiwan Assy Plants
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	Capacity Increase
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes
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7. Timing / schedule

7.1 Date of qualification results	2023-12-15
7.2 Intended start of delivery	2023-12-29
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	
8.2 Qualification report and qualification results	In progress

9. Attachments (additional documentations)

14027 Public product.pdf
14027 Details.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SPC58NN84C3RMHBR	

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PRODUCT/PROCESS CHANGE NOTIFICATION

TITLE	SPC58xN8xC3x (FG84): BGA 17x17 Activation of ASE as Additional Assembly Plant																		
IMPACTED PRODUCTS	FPBGA 17X17X1.8:  FG84 – Bernina 6M																		
MANUFACT. STEP	Assembly																		
INVOLVED PLANT	Subcontractor ASE – Taiwan																		
CHANGE REASON	Service – Dual source & Capacity Improvement. Expansion of current assembly and testing capacity (volumes increase) and flexible/secure production asset – dual sourcing strategy.																		
CHANGE DESCRIPTION	Activation of ASE as additional BE Assembly plant. Here below package Bill Of Material comparison <table border="1" data-bbox="514 1393 1338 1795"> <thead> <tr> <th></th> <th>Malta</th> <th>ASE</th> </tr> </thead> <tbody> <tr> <td>Substrate</td> <td>HL832NS</td> <td>HL832NS</td> </tr> <tr> <td>Glue</td> <td>2000S</td> <td>2100A</td> </tr> <tr> <td>Resin</td> <td>GE-100LF1-2V</td> <td>EME-G750SE</td> </tr> <tr> <td>Wire</td> <td>Cu Pd 0.7 mil</td> <td>Cu Pd Au 0.7 mil</td> </tr> <tr> <td>Package ball</td> <td>Ball Diam 0.55mm / Alloy SACN38855</td> <td>Ball Diam 0.55mm / Alloy SACN38855</td> </tr> </tbody> </table>		Malta	ASE	Substrate	HL832NS	HL832NS	Glue	2000S	2100A	Resin	GE-100LF1-2V	EME-G750SE	Wire	Cu Pd 0.7 mil	Cu Pd Au 0.7 mil	Package ball	Ball Diam 0.55mm / Alloy SACN38855	Ball Diam 0.55mm / Alloy SACN38855
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TRACEABILITY	Dedicated Finished Good Codes																		

VALIDATION	According to ZVEI (AEC-Q100/Q006) recommendations, items: <ul style="list-style-type: none"> - SEM-PA-07 (<i>Die Attach material</i>) - SEM-PA-08 (<i>Change of wire bonding</i>) - SEM-PA-11 (<i>Change of mold compound / encapsulation material</i>) - SEM-PA-18 (<i>Move all or part of production to a different assembly site</i>)
CURRENT PRODUCTS	Current products assembly and testing will be transferred to ASE. ST assembly plants will remain active as alternative solution.
REPORTS	Transfer validation is presently in progress. Transfer validation report will be available within Q4 – 2023
IMPLEMENT.	The Start of Production is foreseen for Q4 - 2023

Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : SPC58xN8xC3x (FG84): BGA 17x17 Activation of ASE as Additional Assembly Plant

PCN Reference : ADG/23/14027

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

SPC58NN84C3RMHBR	SPC58NN84C3RMHBY	
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